

Rev.G Oct.-2018

TO-277

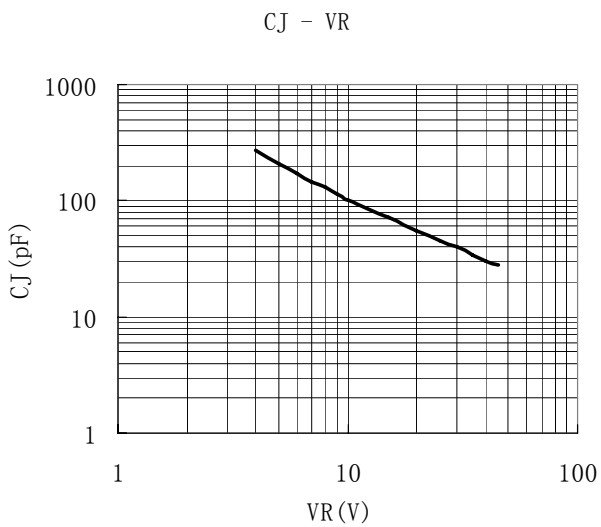
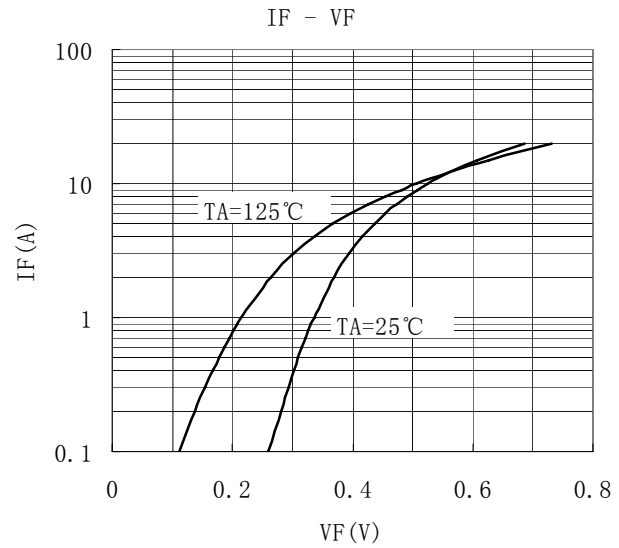
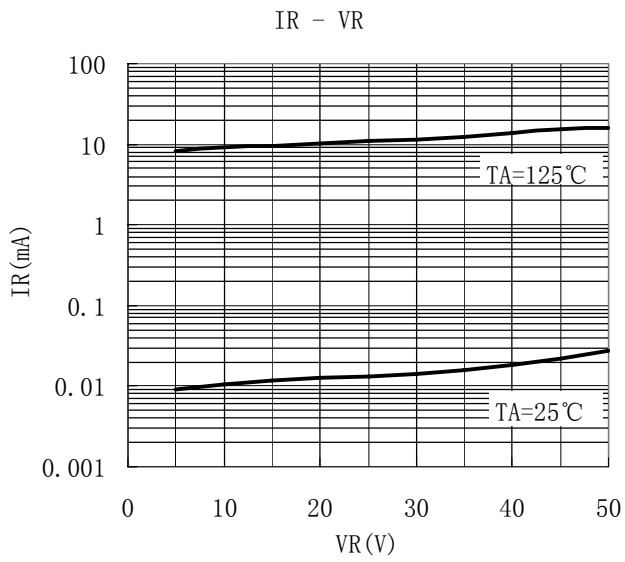
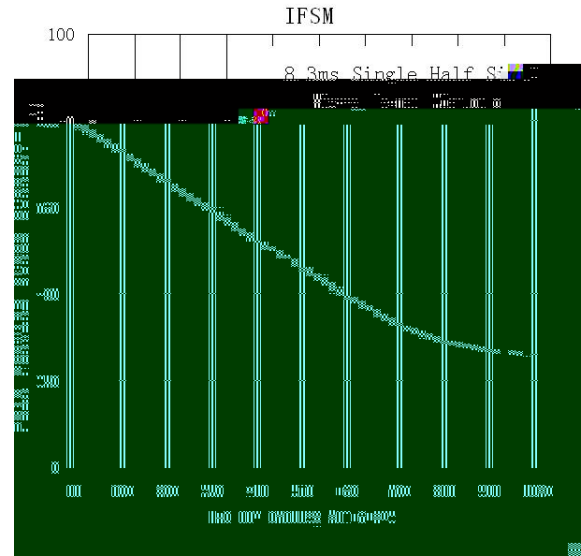
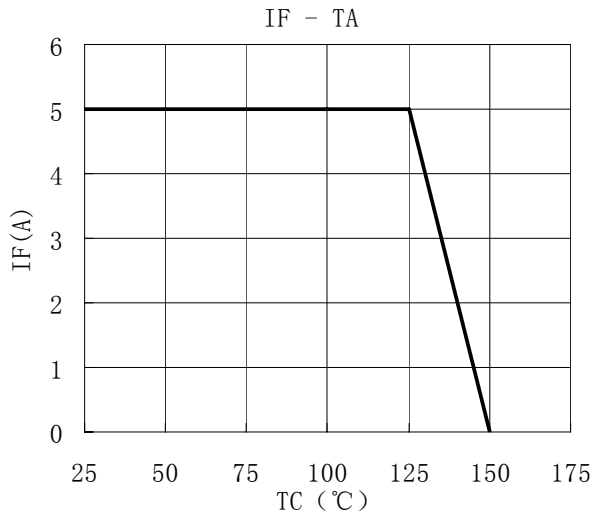
Schottky diode in a TO-277 Plastic Package.

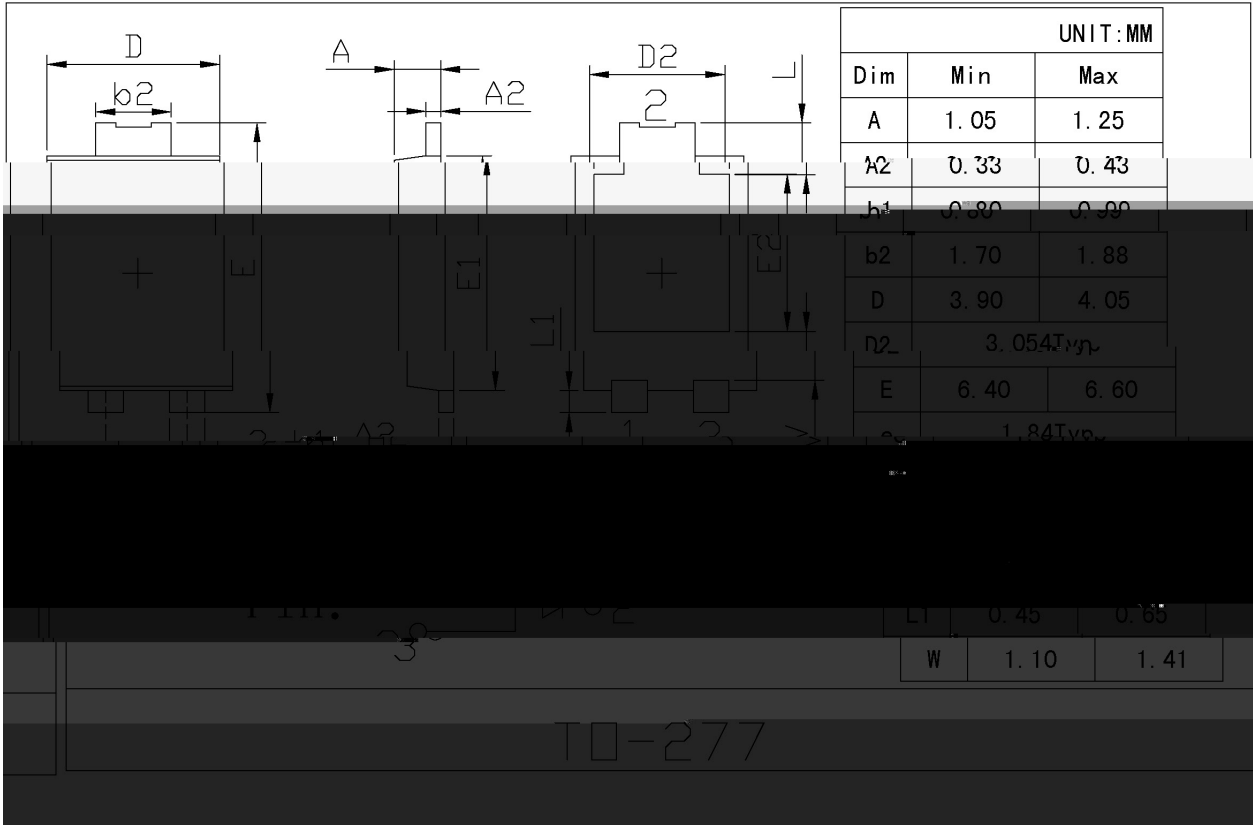
$$V_F(\text{typ})=0.26V$$

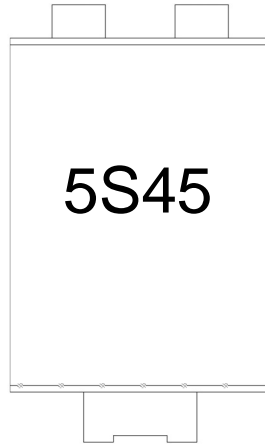
High Forward Surge Capability, Ultra Low Forward Voltage Drop  $V_F$

Parameter	Symbol	Rating	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage Peak Reverse Voltage	$V_{RRM}$ $V_{RWM}$ $V_{RM}$	45	V
RMS Reverse voltage	$V_{R(RMS)}$	31.5	V
Average Rectified Output Current	$I_O$	5	A
Non-Repetitive Peak Forward Surge Current	$I_{FSM}$	80	A
Junction Temperature Range	$T_{j MAX}$	150	
Storage Temperature Range	$T_{stg}$	-55~150	
Typical Thermal Resistance	$R_{JA}$ (Note 1)	73	/W

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Reverse Voltage	$V_R$	$I_R=0.3mA$	45			V
Forward voltage	$V_F$	$I_F=2A$ $T_J=25$		0.37	0.42	V
		$I_F=2A$ $T_J=125$		0.26		V
		$I_F=5A$ $T_J=25$		0.43	0.48	V
		$I_F=5A$ $T_J=125$		0.37		V
Instantaneous Reverse Current	$I_R$ (Note 2)	$V_R=45V$ $T_J=25$		0.02	0.3	mA
		$V_R=35V$ $T_J=85$		1.8	10	mA







5S45

\*\*\*\*

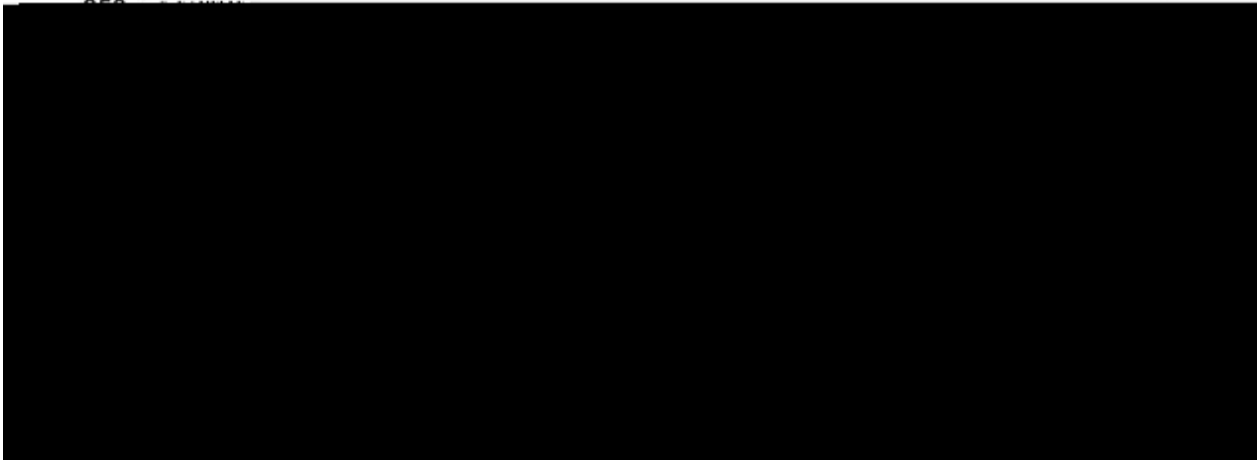
Note:

5S45

\*\*\*\*:

Product Type.

Lot No. Code, code change with Lot No.

**Temperature Profile for IR Reflow Soldering(Pb-Free)**

**Note:**

- |   |           |             |   |
|---|-----------|-------------|---|
| 1 | 150 ~ 180 | 60 ~ 90sec; | 1.Preheating:150~180 , Time:60~90sec.   |
| 2 | 245±5     | 5±0.5sec;   | 2.Peak Temp.:245±5 , Duration:5±0.5sec. |
| 3 | 2 ~ 10    | /sec.       | 3. Cooling Speed: 2~10 /sec.            |

260±5                      10±1 sec.                      Temp.:260±5                      Time:10±1 sec

/ REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm <sup>3</sup> )		
	只卷盘	卷盘盒	只盒	盒箱	只箱		盒	箱
						"		